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(54) **POSITIVE RESIST COMPOSITION AND
PATTERN FORMING METHOD USING THE
SAME**

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430/907

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430/176, 326, 907
See application file for complete search history.

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(57) **ABSTRACT**

A positive resist composition satisfying high sensitivity, high resolution and good line edge roughness at the same time, and a pattern forming method using the composition, are provided, which is a positive resist composition comprising (A) a resin of which solubility in an alkali developer increases under the action of an acid, the resin containing a repeating unit having a specific styrene skeleton and a repeating unit having a specific ring structure, and (B) a compound of generating an acid upon irradiation with actinic rays or radiation; and a pattern forming method using the composition.

20 Claims, No Drawings